

<b>Company</b>		<b>DUNS#</b>	<b>URL For Additional Information</b>
National Semiconductor		04-147-2986	<a href="http://www.national.com/analog/quality/green">http://www.national.com/analog/quality/green</a>

<b>Contact</b>	<b>Title</b>	<b>Phone</b>	<b>Email</b>
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<b>Part Number</b>	<b>MSL Rating</b>	<b>Peak Body Temp C</b>	<b>MaxTime(Sec)</b>	<b>Cycles</b>	<b>Unit Type</b>
LM139AJ/883 MABI	1	NA	NA	NA	Each

<b>Document Date</b>	Contains Lead(Pb) - NOT European RoHS NOT China RoHS Compliant.	<b>Weight (mg)</b>	Does NOT Contain Halogens
01-24-2012		2289.08	

### Material Composition Declaration for Electronic Products

Item	Weight (mg)	Component	CAS#	Weight (mg)	Item-ppm	Part-ppm
Seal Glass	474.000	PbO	1317-36-8	246.053	519,100	107,490
		SnO2	18282-10-5	106.034	223,700	46,322
		ZnO	1314-13-2	55.932	118,000	24,434
		B2O3	1303-86-2	38.584	81,400	16,856
		SiO2	60676-86-0	22.136	46,700	9,670
		Al2O3	1344-28-1	5.261	11,100	2,298
Chip	3.900	Si	7440-21-3	3.877	994,000	1,694
		Al	7429-90-5	0.023	6,000	10
Die Attach	3.770	Ag	7440-22-4	3.016	800,000	1,318
		Lead Borate Glass	65997-18-4	0.754	200,000	329
Leadframe	240.000	Fe	7439-89-6	139.200	580,000	60,811
		Ni	7440-02-0	100.800	420,000	44,035
Ext. LeadFinish	21.300	Sn	7440-31-5	13.419	630,000	5,862
		Pb	7439-92-1	7.881	370,000	3,443
Ceramic Body	1546.000	Al2O3	1344-28-1	1369.292	885,700	598,185
		MnO2	1313-13-9	52.100	33,700	22,760
		SiO2	60676-86-0	44.834	29,000	19,586
		TiO2	13463-67-7	28.756	18,600	12,562
		Cr2O3	1308-38-9	21.489	13,900	9,388
		Fe2O3	1309-37-1	17.408	11,260	7,605
		MgO	1309-48-4	8.086	5,230	3,532
		Co3O4	1308-06-1	4.035	2,610	1,763
Wires	0.107	Al	7429-90-5	0.106	990,000	46
		Si	7440-21-3	0.001	10,000	0

**Note:** The device content disclosed herewith is approximate and is based on engineering estimates only. It has not been verified through analytical testing.

Additionally, the following should be noted:

1. One or more dopant materials may be present in the silicon die at sub-ppm levels to provide semiconductor properties.
2. Epoxy resin components listed are generic and may or may not be the specific compound used, which is considered proprietary.

### RoHS Material Composition Declaration

<b>RoHS Directive 2002/95/EC</b>	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Subject to the limitations below, National Semiconductor Corporation ("National") certifies the following information as of the document date.

1. National products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS"). Certain National products contain lead in RoHS exempt applications 7(a) or 7(c)-1.
2. National products do not contain and are not manufactured with ozone depleting compounds.
3. National products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC") per REACH Regulation (EC) No 1907/2006. National also complies with use restrictions as stipulated in Annex XVII of REACH.
4. National products are manufactured in conformance with National specifications (SC)CSP-9-111C1 Supplier Environmental Requirements for Materials and Products and (SC)CSP-9-111S2 Banned and Reportable Substances.
5. National's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

National has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. National and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release. National's Standard Terms and Conditions of Sale apply to any issue arising out of or in connection with the information provided herein unless otherwise provided by a written contract signed by both parties.

NATIONAL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION.



John L. Conn  
Vice President Quality

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**Banned Substance Monitoring**

<b>Part Number</b>	<b>Document Date</b>
LM139AJ/883 MABI	01-24-2012

Contains Lead(Pb) - NOT European RoHS Compliant.

NOT China RoHS Compliant.

<b>Item#</b>	<b>Material</b>	<b>Cd</b>	<b>CrVI</b>	<b>Pb</b>	<b>Hg</b>	<b>PBB</b>	<b>PBDE</b>	<b>Cl</b>	<b>Br</b>	<b>Ref#</b>
1	CHIP	<1	<1	<1	<30	<10	<10	<75	<50	1000
2	BASE	<2	<2	71425	<2	<5	<5	N/A	N/A	676
3	EXTLF	<2	N/D	367077	<2	<5	<5	<50	<50	57
4	FRAME	<2	<2	<2	<2	<5	<5	N/A	N/A	677
5	LID	<2	<2	71425	<2	<5	<5	N/A	N/A	676
6	WIRE	<2	N/D	<2	<2	<5	<5	N/A	N/A	604

\* Cd: Cadmium, CrVI: Hexavalent Chromium, Pb: Lead, Hg: Mercury, NA: Not Applicable

\* Unless otherwise noted, units are in PPM (parts-per-million)

<b>Ref#</b>	<b>3rd Party Analysis</b> (available upon request, subject to a non-disclosure agreement)
1000	Analysis on 01/24/2011 by Balazs as per Report# 11-00322-00
676	Analysis on 04/29/2011 by SGS per Report# LPCI/04441(B)/11
57	Analysis on 04/29/2011 by SGS per Report# LPCI/04327(B)/11
677	Analysis on 04/29/2011 by SGS per Report# LPCI/04443(B)/11
676	Analysis on 04/29/2011 by SGS per Report# LPCI/04441(B)/11
604	Analysis on 04/29/2011 by SGS per Report# LPCI/04451(B)/11

部件名称 Part	有毒有害物质或元素 Toxic and harmful substances or elements					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
集成电路 Integrated Circuit	X	○	○	○	○	○

**○** : 表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T 11363-2006标准规定的限量要求以下。

**○** : Indicates that this hazardous substance contained in all homogeneous materials of this part is below the limit requirement in SJ/T 11363-2006.

**X** : 表示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T 11363-2006标准规定的限量要求。

**X** : Indicates that this hazardous substance contained in at least one of the homogeneous materials of this part is above the limit requirement in SJ/T 11363-2006.

**美国国家半导体的产品不会含有镉、汞、六价铬、多溴联苯(PBB)和二苯醚(PBDE)。**

National Semiconductor's products will not contain cadmium, mercury, hexavalent chromium, polybrominated biphenyls (PBBs) and diphenyl ether (PBDE).



**环保使用期限(epup)** 是指以符号在这里展出. 环保使用期限(epup)的有效期只有当产品使用范围以内的数据表中的规格.

The Environmental Protection Use Period (EPUP) is defined by the symbol shown here. The Environmental Protection Use Period (EPUP) is valid only when product is used within the limits of the data sheet specifications.